

# SOT820-1

plastic thermal enhanced small outline package; 16 leads;  
body width 7.5 mm; heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSOP16
<b>Package type industry code</b>	HSOP16
<b>Package style descriptive code</b>	HSOP (heatsink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-5-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	10.1	-	10.3	10.5	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.5	2.5	mm
A <sub>2</sub>	package height	2.25	-	2.35	2.45	mm
n <sub>2</sub>	actual quantity of termination	-	-	16	-	



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## 2. Package outline

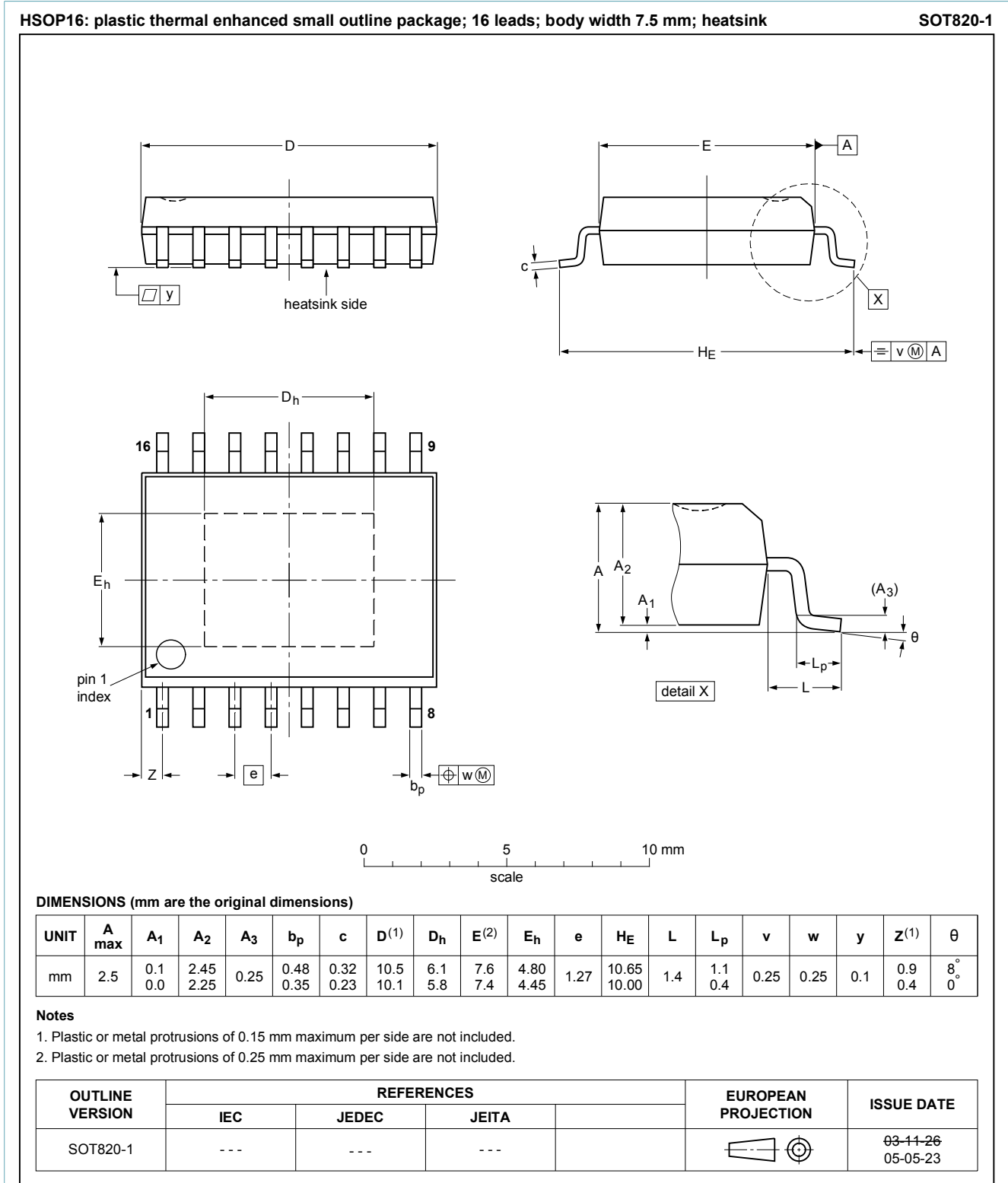


Fig. 1. Package outline HSOP16 (SOT820-1)

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### 3. Legal information

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## 4. Contents

---

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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